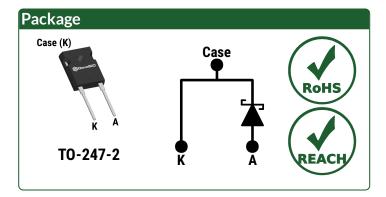
# Silicon Carbide Schottky Diode



 $V_{RRM}$  = 1200 V  $I_{F(T_C = 156^{\circ}C)}$  = 10 A  $Q_C$  = 32 nC

#### **Features**

- Gen4 Thin Chip Technology for Low V<sub>F</sub>
- Superior Figure of Merit Qc\*V<sub>F</sub>
- 100% Avalanche (UIL) Tested
- Enhanced Surge Current Withstand Capability
- Temperature Independent Fast Switching
- Low Thermal Resistance
- Positive Temperature Coefficient of V<sub>F</sub>
- High dV/dt Ruggedness



### Advantages

- Improved System Efficiency
- High System Reliability
- Optimal Price Performance
- Reduced Cooling Requirements
- Increased System Power Density
- Zero Reverse Recovery Current
- Easy to Parallel without Thermal Runaway
- Enables Extremely Fast Switching

#### **Applications**

- Power Factor Correction (PFC)
- Solar Inverters
- Battery Chargers
- High Frequency Converters
- Switched Mode Power Supply (SMPS)
- AC/DC Power Supplies
- Anti-Parallel / Free-Wheeling Diode
- LED and HID Lighting

Absolute Maximum Ratings (At T <sub>C</sub> = 25°C Unless Otherwise Stated)								
Parameter	Symbol	Conditions	Values	Unit	Note			
Repetitive Peak Reverse Voltage	$V_{RRM}$		1200	٧				
	I <sub>F</sub>	T <sub>C</sub> = 100°C, D = 1	23					
Continuous Forward Current		$T_C = 135^{\circ}C, D = 1$	16	Α	Fig. 4			
		$T_C = 156^{\circ}C, D = 1$	10					
Non-Repetitive Peak Forward Surge Current, Half Sine	IF,SM	$T_C$ = 25°C, $t_P$ = 10 ms	80	А				
Wave		$T_C$ = 150°C, $t_P$ = 10 ms	64					
Repetitive Peak Forward Surge Current, Half Sine Wave	I <sub>F,RM</sub>	$T_C$ = 25°C, $t_P$ = 10 ms	48	٨				
		$T_C$ = 150°C, $t_P$ = 10 ms	33	Α				
Non-Repetitive Peak Forward Surge Current	I <sub>F,MAX</sub>	T <sub>C</sub> = 25°C, t <sub>P</sub> = 10 μs	400	Α				
i <sup>2</sup> t Value	∫i²dt	$T_C$ = 25°C, $t_P$ = 10 ms	32	A <sup>2</sup> s				
Non-Repetitive Avalanche Energy	E <sub>AS</sub>	L = 1.8 mH, I <sub>AS</sub> = 10 A	91	mJ				
Diode Ruggedness	dV/dt	V <sub>R</sub> = 0 ~ 960 V	200	V/ns				
Power Dissipation	Ртот	T <sub>C</sub> = 25°C	149	W	Fig. 3			
Operating and Storage Temperature	$T_j$ , $T_{stg}$		-55 to 175	°C				



<b>Electrical Characteristics</b>								
Parameter	Symbol	Conditions -		Values			Unit	Note
	Зуший			Min.	Тур.	Max.	Ollit	Note
Diode Forward Voltage	V <sub>F</sub>	I <sub>F</sub> = 10 A, T <sub>j</sub> = 25°C			1.5	1.8	٧	Fig. 1
	۷F	$I_F = 10 \text{ A}, T_j = 175^{\circ}\text{C}$			1.9			
Reverse Current	l <sub>a</sub>	V <sub>R</sub> = 1200 V, T <sub>j</sub> = 25°C			1	10		Fig. 2
	IR	$V_R = 1200 \text{ V, } T_j = 175^{\circ}\text{C}$			7		μA	Fig. 2
Total Capacitive Charge	Qc		$V_{R} = 400 \text{ V}$		22		nC	Fig. 7
	QU	l <sub>F</sub> ≤ I <sub>F,MAX</sub> dI <sub>F</sub> /dt = 200 A/μs	$V_{R} = 800 V$		32		IIC	
Switching Time	t <sub>o</sub>		$V_{R} = 400 \text{ V}$		< 10		ns	
	ts		$V_{R} = 800 V$		<b>\ 10</b>		115	
Total Capacitance	С	$V_R$ = 1 V, f = 1MHz $V_R$ = 800 V, f = 1MHz			367		nΕ	Fig. 6
					21		pF	

Thermal/Package Characteristics								
Parameter	Symbol	Conditions	Values			Heit	Note	
		Conditions	Min.	Тур.	Max.	- Unit	Note	
Thermal Resistance, Junction - Case	$R_{thJC}$			1.0		°C/W	Fig. 9	
Weight	W <sub>T</sub>			6.0		g		
Mounting Torque	T <sub>M</sub>	Screws to Heatsink			1.1	Nm		





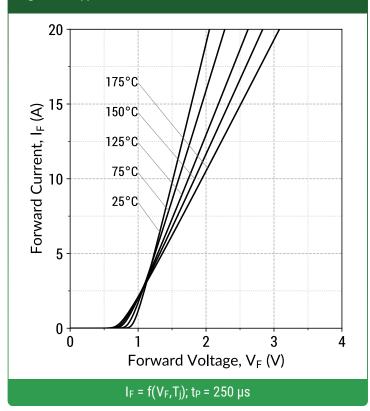


Figure 2: Typical Reverse Characteristics

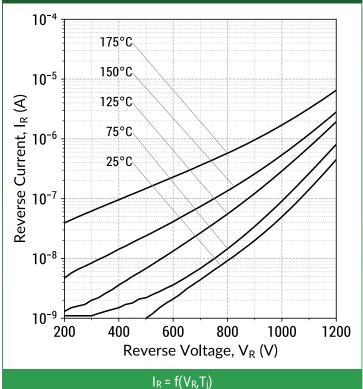


Figure 3: Power Derating Curves

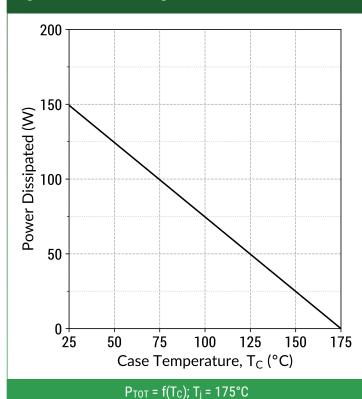
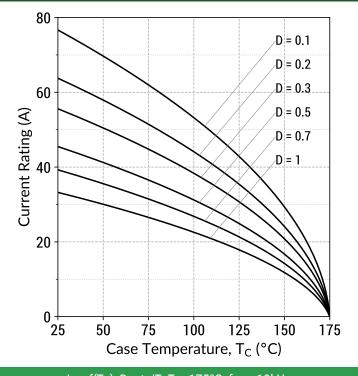


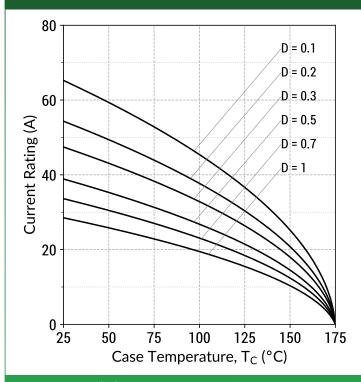
Figure 4: Current Derating Curves (Typical V<sub>F</sub>)



 $I_F = f(T_C)$ ; D =  $t_P/T$ ;  $T_j \le 175$ °C;  $f_{SW} > 10$ kHz

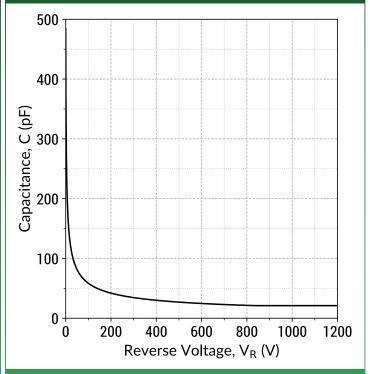


Figure 5: Current Derating Curves (Maximum V<sub>F</sub>)



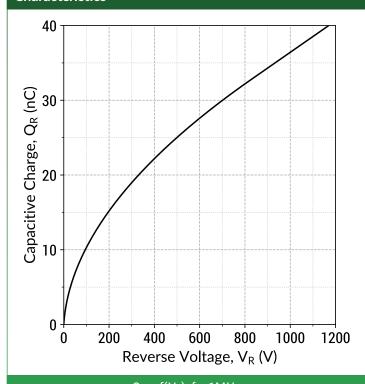
 $I_F = f(T_C)$ ; D =  $t_P/T$ ;  $T_j \le 175$ °C;  $f_{SW} > 10$ kHz

Figure 6: Typical Junction Capacitance vs Reverse Voltage Characteristics



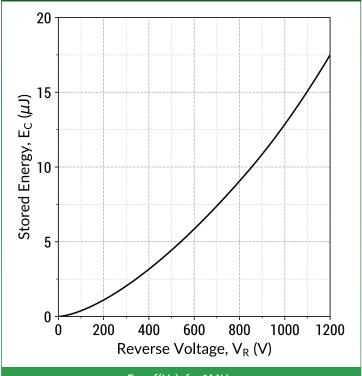
 $C = f(V_R); f = 1MHz$ 

Figure 7: Typical Capacitive Charge vs Reverse Voltage Characteristics



 $Q_C = f(V_R)$ ; f = 1MHz

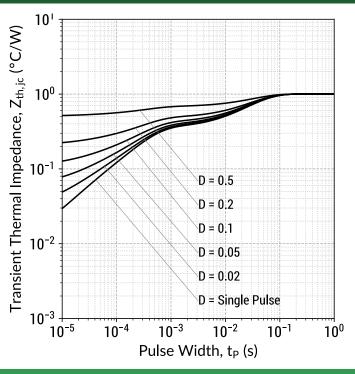
Figure 8: Typical Capacitive Energy vs Reverse Voltage Characteristics



 $E_C = f(V_R)$ ; f = 1MHz

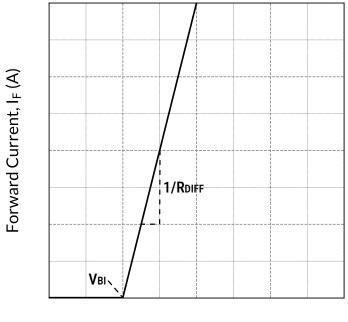


Figure 9: Transient Thermal Impedance



 $Z_{th,jc} = f(t_P,D); D = t_P/T$ 

Figure 10: Forward Curve Model



Forward Voltage, V<sub>F</sub> (V)

 $I_F = f(V_F, T_j)$ 

### Forward Curve Model Equation:

 $I_F = (V_F - V_{BI})/R_{DIFF} (A)$ 

### Built-In Voltage (V<sub>BI</sub>):

$$V_{BI}(T_j) = m \times T_j + n (V)$$
  
 $m = -0.00119 (V/^{\circ}C)$   
 $n = 1.01 (V)$ 

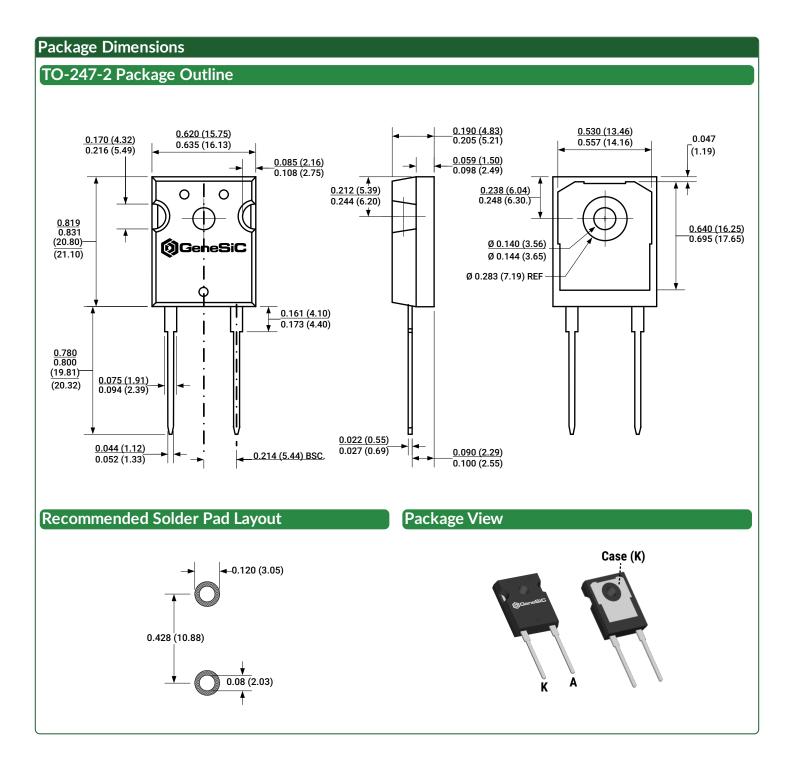
### Differential Resistance (RDIFF):

$$R_{DIFF}(T_j) = a \times T_j^2 + b \times T_j + c (\Omega)$$
  
 $a = 1.19e-06 (\Omega/^{\circ}C^2)$   
 $b = 0.000165 (\Omega/^{\circ}C)$   
 $c = 0.049 (\Omega)$ 

### **Forward Power Loss Equation:**

$$P_{LOSS} = V_{BI}(T_j) \times I_{AVG} + R_{DIFF}(T_j) \times I_{RMS}^2$$





#### **NOTE**

- 1. CONTROLLED DIMENSION IS INCH. DIMENSION IN BRACKET IS MILLIMETER.
- 2. DIMENSIONS DO NOT INCLUDE END FLASH, MOLD FLASH, MATERIAL PROTRUSIONS.





### Compliance

#### **RoHS Compliance**

The levels of RoHS restricted materials in this product are below the maximum concentration values (also referred to as the threshold limits) permitted for such substances, or are used in an exempted application, in accordance with EU Directive 2011/65/EC (RoHS 2), as adopted by EU member states on January 2, 2013 and amended on March 31, 2015 by EU Directive 2015/863. RoHS Declarations for this product can be obtained from your GeneSiC representative.

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REACH substances of high concern (SVHCs) information is available for this product. Since the European Chemical Agency (ECHA) has published notice of their intent to frequently revise the SVHC listing for the foreseeable future, please contact a GeneSiC representative to insure you get the most up-to-date REACH SVHC Declaration. REACH banned substance information (REACH Article 67) is also available upon request.

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#### **Revision History**

Rev 21/Jul: Updated with most recent data

Supersedes: Rev 21/May



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